

Desoldering Wire BGA Wick PCB

Preparation

1. Clean the PCB with isopropyl alcohol to remove any flux residue.
2. Pre-heat the PCB to 150°C to pre-heat the BGA.
4. Use the wick to absorb the molten solder. Heat the BGA with a heat gun or reflow oven. The wick will absorb the solder as it melts. Sn63 (60% Sn, 40% Pb) is recommended for this process.

Procedure

1. Heat the BGA with a heat gun or reflow oven.
2. Apply the wick to the BGA. The wick will absorb the molten solder. **excess** solder will be absorbed by the wick.
3. **Therm**, the temperature of the BGA will rise. **residu** solder will be absorbed by the wick.
4. The BGA will be removed from the PCB.

PRODUCT DISPLAY



PRODUCT SIZE



PRODUCT FEATURES



FRONT



BACK



Features:

1. High quality alloy copper wire from the precision weaving.
2. For the removal of tin in the excess solder, resistance to oxidation and corrosion.
3. Thermal conductivity, tin effect is very good, tin suction clean. Low residue.
4. Suitable for precision circuit using.

PRODUCT PHOTOGRAPH

WELGHT:7.5G

LENGTH:1.5M
WIDTH:1.5MM





